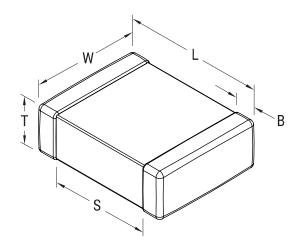




SMD Comm X8G HT150C Flex, Ceramic, 0.01 uF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

0.01 uF

1%

1 kHz 1.0Vrms

200 VDC

500 VDC -55/+150°C

30 ppm/C, 1kHz 1.0Vrms

0% Loss/Decade Hour: Referee Time is 1000 Hours

0.1% 1 kHz 1.0Vrms

100 GOhms

X8G

		Specifications
	1210	Capacitance
	3.3mm +/-0.4mm	Measurement Condition
	2.6mm +/-0.3mm	Tolerance
	0.78mm +/-0.20mm	Voltage DC
	1.5mm MIN	Dielectric Withstanding Voltage
	0.6mm +/-0.25mm	Temperature Range
		Temp. Coefficient
ifications		Capacitance Change with
	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC

0.78mm +/-0.20mm	Voltage DC
1.5mm MIN	Dielectric Withstanding Voltage
0.6mm +/-0.25mm	Temperature Range
	Temp. Coefficient
T&R, 330mm, Plastic Tape 10000	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)
	Dissipation Factor
	Aging Rate

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions

Packaging Speci

Packaging Quantity

Packaging

Chip Size

L W

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